L Number	Hits	Search Text	DB	Time stamp
-	1563	(solder near3 length) or (solder near3 segment$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/13 11:29
-	2345054	connector or connecting or interposer or interconnect or interconnecting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/13 11:25
-	822	((solder near3 length) or (solder near3 segment$1)) and (connector or connecting or interposer or interconnect or interconnecting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/13 11:12
-	642	(((solder near3 length) or (solder near3 segment$1)) and (connector or connecting or interposer or interconnect or interconnecting)) and (substrate or board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/13 11:23
-	180	(((solder near3 length) or (solder near3 segment$1)) and (connector or connecting or interposer or interconnect or interconnecting)) not (((((solder near3 length) or (solder near3 segment$1)) and (connector or connecting or interposer or interconnect or interconnecting)) and (substrate or board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/13 11:27
-	20	solder with bearing with wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/13 11:54
-	1	solder adj bearing adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/13 11:32
-	5500	solder and substrate and groove	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/13 11:33
-	3697	(connector or connecting or interposer or interconnect or interconnecting) and (solder and substrate and groove)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/13 11:33
-	56	((connector or connecting or interposer or interconnect or interconnecting) and (solder and substrate and groove)) and ((solder near3 length) or (solder near3 segment$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/13 11:33
-	3	solder near3 bearing near3 wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/13 11:55
-	16	(solder adj bearing or solder-bearing) near3 substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 12:07
-	1	(wafer) near3 (groove) near3 (solder)	USPAT	2004/08/17 16:25
-	14	(wafer) with (groove) with (solder)	USPAT	2004/08/17 16:26
-	10	(wafer) with (channel$1) with (solder)	USPAT	2004/08/17 16:30
-	20	(wafer) with (groove$1) with (solder)	USPAT	2004/08/17 16:26
-	30	((wafer) with (groove) with (solder)) or ((wafer) with (channel$1) with (solder)) or ((wafer) with (groove$1) with (solder))	USPAT	2004/08/17 16:26

-	24	(interconnect or interposer) with (channel$1 or groove$1) with (solder)	USPAT	2004/08/17 16:35
-	23	((interconnect or interposer) with (channel$1 or groove$1) with (solder)) not (((wafer) with (groove) with (solder)) or ((wafer) with (channel$1) with (solder)) or ((wafer) with (groove$1) with (solder)))	USPAT	2004/08/17 16:31
-	104	(interconnect or interposer or wafer) with (channel$1 or groove$1) with (solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/17 16:35
-	51	((interconnect or interposer or wafer) with (channel$1 or groove$1) with (solder)) not (((interconnect or interposer) with (channel$1 or groove$1) with (solder)) or ((wafer) with (groove$1) with (solder)) or ((wafer) with (channel$1) with (solder)) or ((wafer) with (groove) with (solder)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/17 16:36